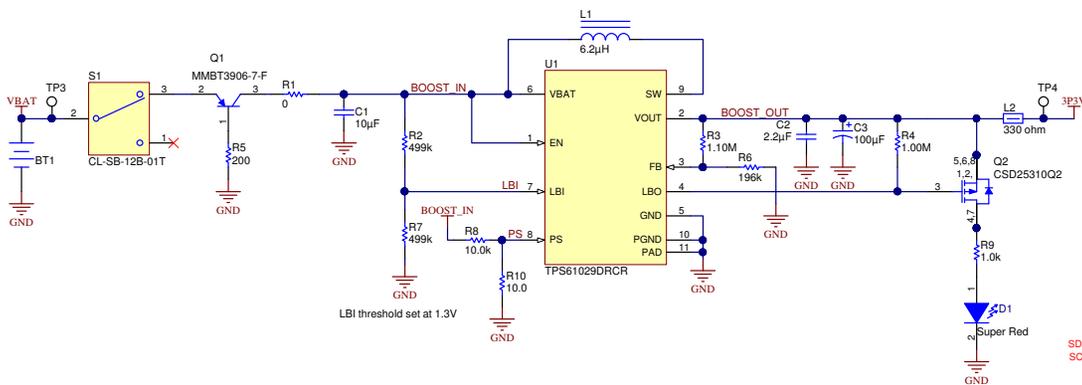
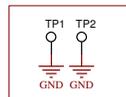


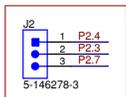
+3.3V Boost Output



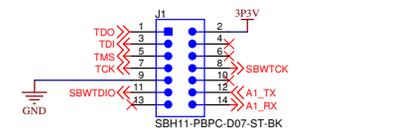
Testpoints



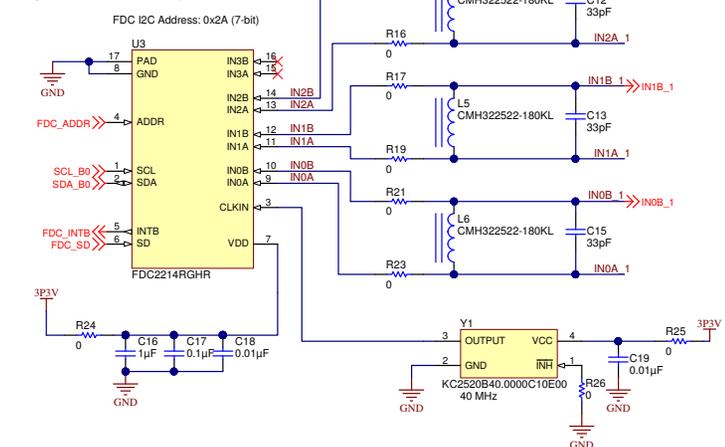
GPIO Pins



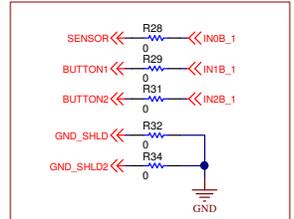
JTAG



Capacitance-to-Digital Converter



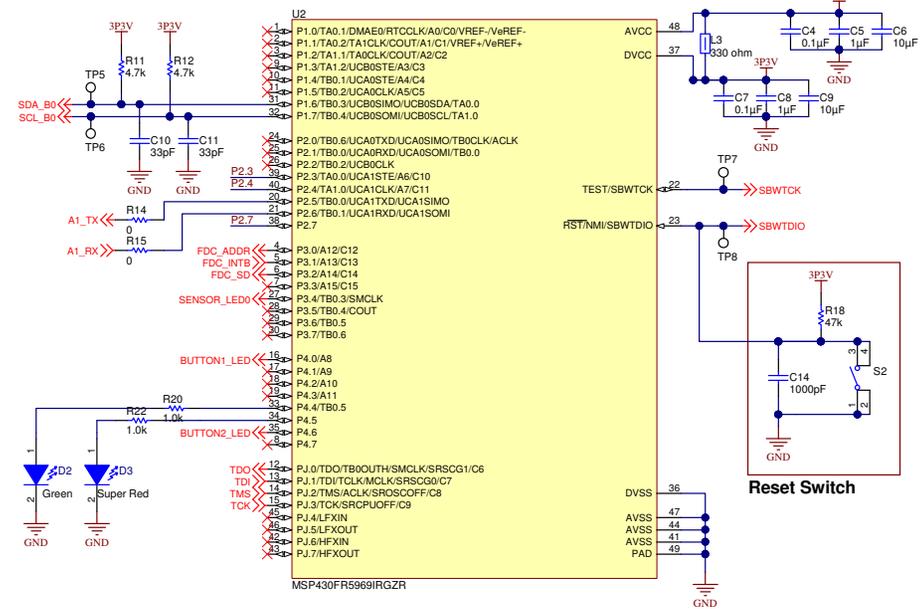
SENSOR and SHLD Selection



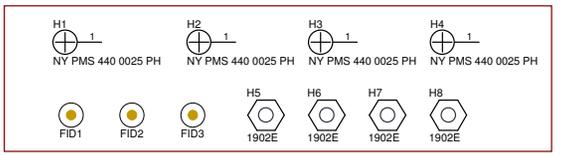
PCB LOGO
Texas Instruments
Pb-Free Symbol
FCC disclaimer

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only
ZZ2
Assembly Note
Provide H1, H2, H3, H4, H5, H6, H7, H8 as loose parts.

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Hardware



Orderable: FDC2214PROXSEN-EV	Designed for: Public Release	Mod. Date: 10/5/2015
TID #: TIDA-00466	Project Title: FDC2214 Proximity and Capacitive Touch Sensing	
Number: [Rev: A]	Assembly Title:	Sheet: 1 of 1
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Size: B
Drawn By: [Name]	File: TIDA00466.SchDoc	http://www.ti.com
Engineer: David Wang	Contact: http://www.ti.com/support	© Texas Instruments 2015

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